

**IN THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

Claims 2 and 3 have been amended as follows:

**Listing of Claims:**

Claim 1 (original): A solid electrolytic capacitor comprising a capacitor element in which a dielectric coating layer and a cathode layer are sequentially formed on a surface of an anode element having an anode lead member planted on one end surface thereof, an anode terminal connected with the anode lead member, a platy cathode terminal mounting the capacitor element thereon and connected with the cathode layer, and an enclosure resin coating the capacitor element, a part of the cathode terminal and a part of the anode terminal being exposed on a same plane from the enclosure resin,

wherein the cathode terminal is provided with a cathode exposed portion exposed from the enclosure resin in at least two locations on the same plane.

Claim 2 (currently amended): A solid electrolytic capacitor according to claim 1, wherein the cathode exposed portion comprises a first cathode exposed portion and a second cathode exposed portion, and the first cathode exposed portion is formed in a closer location to [[the]] an anode exposed portion than the second cathode exposed portion is.

Claim 3 (currently amended): A solid electrolytic capacitor according to claim 2, wherein the first cathode exposed portion extends to end portions of the solid electrolytic capacitor in a

transverse direction on the same plane.

Claim 4 (original): A mounting method for a solid electrolytic capacitor according to claim 1, claim 2 or claim 3 for fixing the solid electrolytic capacitor to a circuit board through a solder, wherein the circuit board has lands each provided in a position corresponding to each of the anode exposed portion and cathode exposed portion, and the solder is pasted on each of the lands to solder the solid electrolytic capacitor to the circuit board.